



DEFENSE LOGISTICS AGENCY
 LAND AND MARITIME
 POST OFFICE BOX 3990
 COLUMBUS, OH 43218-3990

December 5, 2011

Mr. John DeBrita
 DDI Global Corp - Anaheim
 1220 N. Simon Circle
 Anaheim, CA 92806

Dear Mr. DeBrita:

RE: Notification of Qualification, MIL-PRF-31032, CAGE: 0BSG1, VQ(VQE-12-023613),
 CN#035026 (adjustment/new format of VQ(VQE-09-018147))

Qualification of your products is granted under the current issue of the specification as a result of successful qualification testing to Department of Defense Performance Specification MIL-PRF-31032, Printed Circuit Board/Printed Wiring Board, and associated specification MIL-PRF-31032 /1 & /2. The material and classification indicated below shall be listed on Qualified Manufacturers List QML-31032.

MANUFACTURER INFORMATION DDI Global Corp. - Anaheim 1220 N. Simon Circle, Anaheim, CA, 92806 US	PLANT LOCATION Same Address as Manufacturer	CAGE Code: 0BSG1 Mr. John DeBrita Phone: 714 688-7296 Email: jdebrita@ddiglobal.com
CAPABILITIES BY TECHNOLOGY / ASSOCIATED SPECIFICATION		
Specification: MIL-PRF-31032/1, MIL-PRF 31032/2		QUALIFICATION LETTERS:
Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant Max. Panel Size: 18" x 24" Max. Number of Layers: 10 Max. Board Thickness: .1" Min. Hole Size: .32" Drilled Plated-Through Hole Before Plating Aspect Ratio: 3:1 Through-Hole Min. Conductor Width/Space: .01"/.01" Hole Preparation: Plasma Desmear, Plasma Etchback Hole Wall Conductive Coating: Electroless Copper Copper Plating: Direct Current Plate Solder Resist: Liquid Photoimageable Finish System: ENIG, HASL Additional Fab Capabilities: Foil Lamination Controlled Impedance: Differential, Single-Ended		VQ-09-018147 (initial)

MANUFACTURER INFORMATION DDI Global Corp. - Anaheim 1220 N. Simon Circle, Anaheim, CA, 92806 US	PLANT LOCATION Same Address as Manufacturer	CAGE Code: 0BSG1 Mr. John DeBrita Phone: 714 688-7296 Email: jdebrita@ddiglobal.com
CAPABILITIES BY TECHNOLOGY / ASSOCIATED SPECIFICATION		
Specification: MIL-PRF-31032/1, MIL-PRF 31032/2		QUALIFICATION LETTERS:
Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant Max. Panel Size: 18" x 24" Max. Number of Layers: 22 Max. Board Thickness: .115" Min. Hole Size: .009" Drilled Plated-Through Hole Aspect Ratio: 10:1 Through-Hole Min. Conductor Width/Space: .004"/.006" Hole Preparation: Plasma Desmear, Plasma Etchback Hole Wall Conductive Coating: Electroless Copper Copper Plating: Direct Current Plate Hole Fill/Via Plug: Conductive, Non-Conductive Solder Resist: Liquid Photoimageable Finish System: ENIG, HASL Additional Fab Capabilities: Foil Lamination Blind Vias Buried Vias Controlled Impedance: Differential, Single-Ended		VQ-09-018147 (initial)

This qualification is based on your MIL-PRF-31032 certification and is subject to the conditions:

1. A listing on the Qualified Manufacturers List (QML) does not guarantee acceptance of the product(s) in any future purchase.
2. QML listing does not constitute a waiver of any requirements of the specification or of the provisions of any contract.
3. Advertising of qualification information is permitted. Permission to use such information for advertising or publicity purposes is granted provided that such publicity or advertising does not state or imply that the product(s) is the only product of that type qualified or that the Department of Defense in any way recommends or endorses the manufacturer's product.
4. The listing applies only to products produced in the plant(s) specified in this letter of notification of qualification and applies to future amendments or revisions of the specification, unless otherwise notified.
5. The listing applies only to materials and manufacturing construction techniques identical to or covered by that (those) qualified. The qualifying activity must be advised in advance of any change to the materials and manufacturing construction techniques. Failure to notify the qualifying activity

of any change to the materials and manufacturing construction techniques is cause for removal from the QML.

Manufacturers are required to inform this office immediately if a failure occurs during PCI or CVI testing, if production of this qualification is discontinued, or prior to issuance of a GIDEP Alert and/or Problem Advisory on their QML products.

Because we are held responsible for the accuracy and currency of this QML, please let us know if your company discontinues production utilizing these materials or processes. If you have any questions, please contact Mr. Jeffrey Ciesla, (614) 692-0624.

Sincerely,

A handwritten signature in blue ink, appearing to read 'J Gemperline', with the initials 'JG' written below it.

JOSEPH GEMPERLINE

Chief

Sourcing and Qualifications Division

